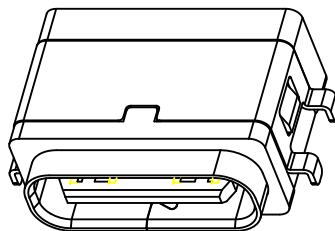
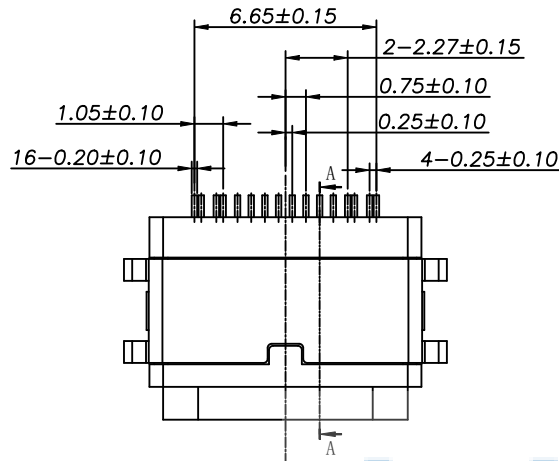


| REV. | ECN NO | CONTENT         | DATE | ENGINEER |
|------|--------|-----------------|------|----------|
| A0   |        | Initial release | /    | SGF      |



NOTE:

- MATERIAL SPECIFICATION:
  - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
  - COVER: STAINLESS STEEL.
  - CONTACTS: COPPER ALLOY
  - MID PLATE: STAINLESS STEEL
  - SHELL: STAINLESS STEEL
  - O-RING: SILICONE RUBBER,BLACK
- PLATING SPECIFICATION:
  - CONTACTS:
 

Ni 50u" MIN. UNDER PLATED OVER ALL.

SEE TABLE 1 ON THE FUNCTIONAL AREA OF CONTACT.

SEE TABLE 1 ON THE SOLDER AREA OF CONTACT.
  - SHELL:
 

Ni 30u" MIN. UNDER PLATED OVER ALL.
  - COVER:
 

Ni 30u" MIN. UNDER PLATED OVER ALL.
  - MID PLATE:
 

CLEAR ONLY.
- MECHANICAL PERFORMANCE,
  - INSERTION FORCE: 5~20N.
  - REMOVAL FORCE: 8~20N.
  - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
  - CURRENT RATING:5.0A  
VOLTAGE RATING:5.0V
  - LLCR:
 

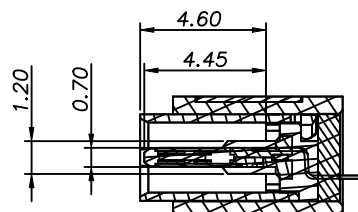
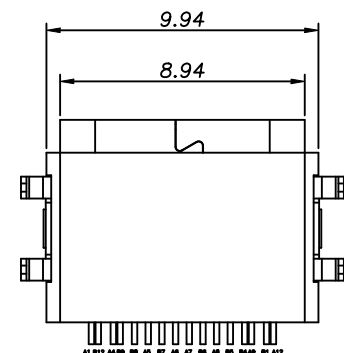
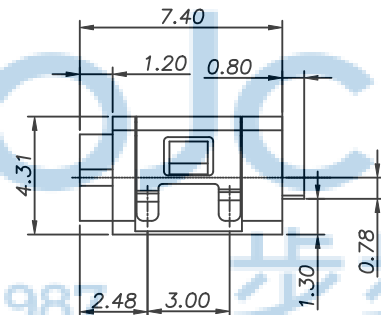
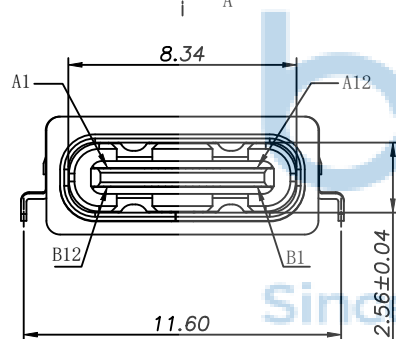
VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.

SHIELD: 50mA/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mA.
  - INSULATION RESISTANCE: 100MΩ MIN
  - DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 

OPERATING TEMPERATURE: -25℃~+85℃.
- IR REFLOW:
 

THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260℃.
- WATER PROOFNESS:THISPRODUCTIS BASED ON IPX7.

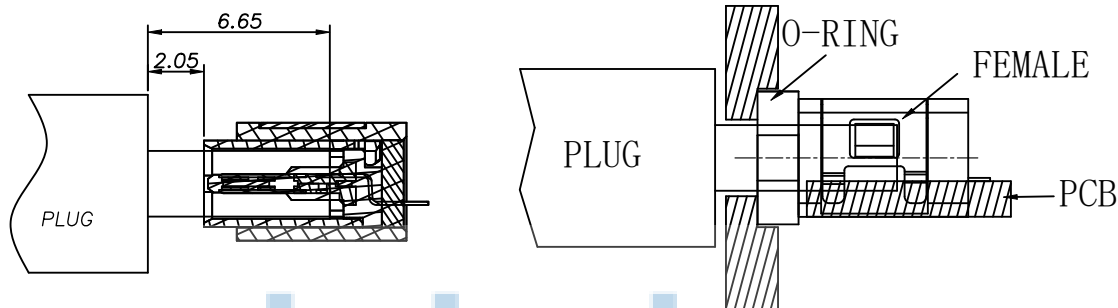


SECTION:A-A



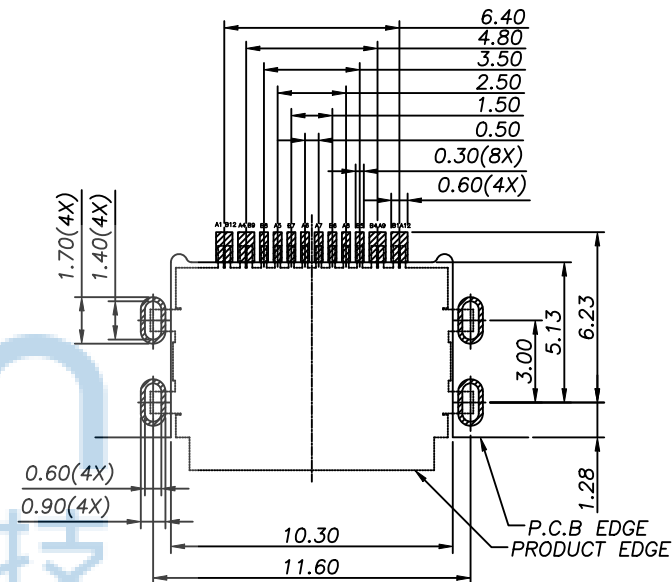
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|                                        |                                  |                                                                          |                              |
|----------------------------------------|----------------------------------|--------------------------------------------------------------------------|------------------------------|
| 深圳市步步精科技有限公司                           |                                  | NAME: TYPE-C 16P 防水母座 端子SMT 四脚DIP 沉板1.30<br>L=7.40 CH=0.78 IPX7 不带防水圈 编带 |                              |
| .X: ±0.38<br>.XX: ±0.25<br>.XXX: ±0.13 | X': ±3'<br>.X': ±2'<br>.XX': ±1' | APPD. JM_Zheng                                                           | P.J. NO.: 126-221-160002-J8G |
| CHKD. LYX                              | DR. SGF                          | SCALE: N/A                                                               | REV.: A0                     |
| FINISH: SEE NOTES                      | MAT'L: SEE NOTES                 | UNIT: mm                                                                 | PAGE: 1/3                    |



AFTER MATING

组装面板防水示意图



RECOMMENDED P.C.B. LAYOUT  
TOLERANCE UNSPECIFIED  $\pm 0.05\text{mm}$

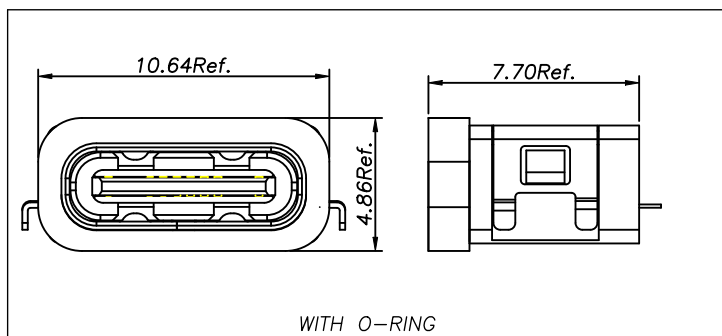
# USB TYPE-C PIN ASSIGNMENTS

|     |             |     |             |
|-----|-------------|-----|-------------|
| A1  | GND         | B12 | GND         |
| A4  | VBUS        | B9  | VBUS        |
| A5  | CC1         | B8  | SBU2        |
| A6  | DP1         | B7  | DN2         |
| A7  | DN1         | B6  | DP2         |
| A8  | SBU1        | B5  | CC2         |
| A9  | VBUS        | B4  | VBUS        |
| A12 | GND         | B1  | GND         |
| PIN | SIGNAL NAME | PIN | SIGNAL NAME |



TABLE 1

| ITEM | CONTACTS | CONTACTS        |             |
|------|----------|-----------------|-------------|
|      |          | FUNCTIONAL AREA | SOLDER AREA |
| 1    | C1815    | Au:3u"          | Au:G/F      |
| 2    | C1815    | Au:1u"          | Au:G/F      |



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PDWG.NO: 0338-1

深圳市步步精科技有限公司

NAME: TYPE-C 16P 防水母座 端子SMT 四脚DIP 沉板1.30  
L=7.40 CH=0.78 1PX7 不带防水圈 编带

PJ. NO.: 126-221-160002-J8G

SIZE: A4 DRW NO.:

FINISH: SEE NOTES MAT'L: SEE NOTES

SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/3

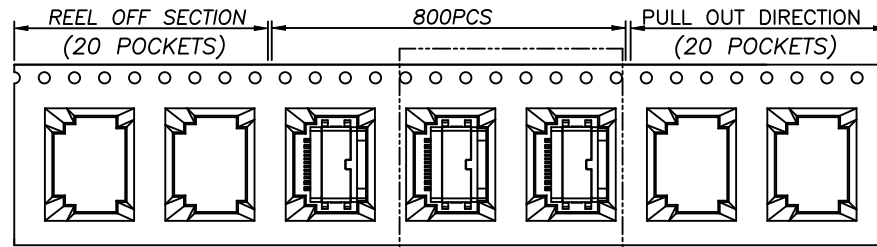
APPD. JM\_Zheng

CHKD. LYX

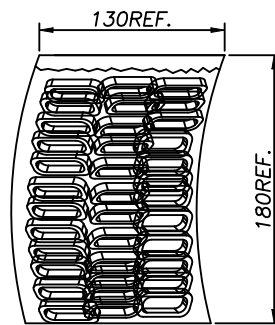
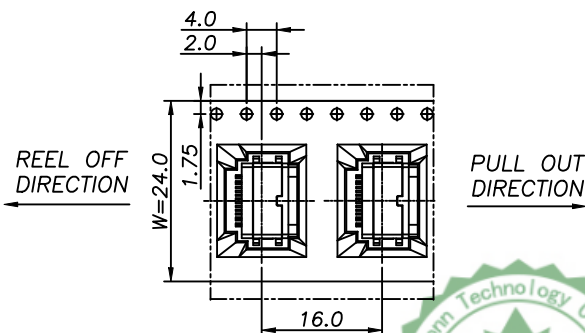
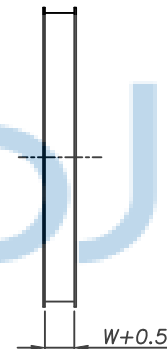
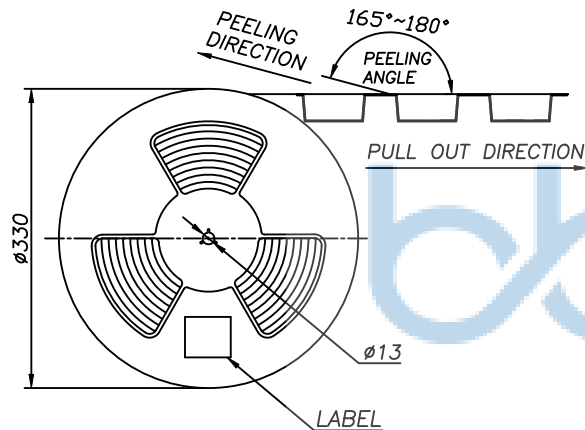
DR. SGF



| REV. | ECN NO | CONTENT         | DATE | ENGINEER |
|------|--------|-----------------|------|----------|
| A0   |        | Initial release | /    | SGF      |



SEE DETAIL X



1000PCS/BAG  
O-RING

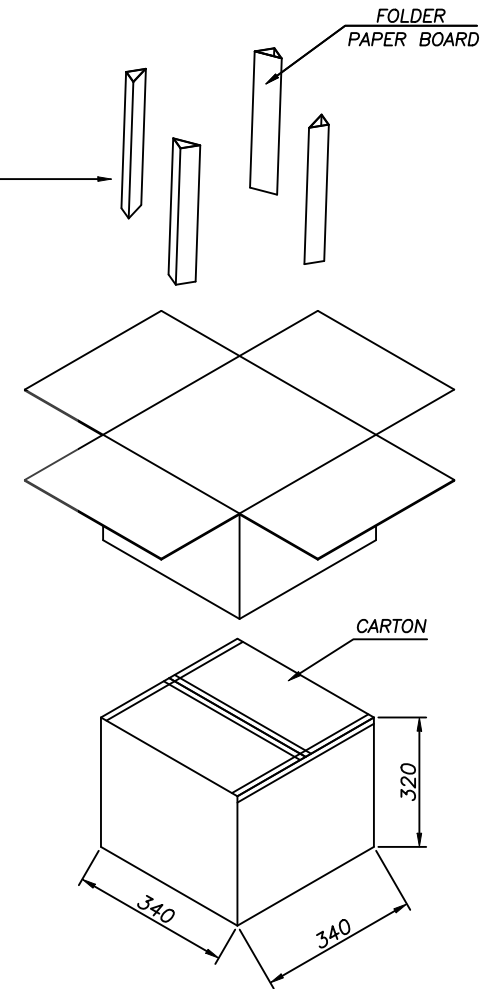
PAPER BOARD

REEL AND TAPE

REEL AND TAPE

PAPER BOARD

O-RING



|                 | REEL | CARTON |
|-----------------|------|--------|
| CONNECTOR (PCS) | 800  | 8000   |

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|                                        |                                 |                                                                          |                                                   |
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| .X: ±0.38<br>.XX: ±0.25<br>.XXX: ±0.13 | X': ±3'<br>X': ±2'<br>.XX': ±1' | PJ. NO.: 126-221-160002-J8G<br>SIZE: A4 DRW NO.:                         | FINISH: SEE NOTES<br>SCALE: N/A REV.: A0 UNIT: mm |
| APPD. JM_Zheng                         | CHKD. LYX                       | MAT'L: SEE NOTES<br>PAGE: 3/3                                            |                                                   |
| DR. SGF                                |                                 |                                                                          |                                                   |

